

ABSTRACT

Disclosed is a socket device for testing a circuit of an electronic device, the socket device having a structure that combines a MEMS pin and metal powder and thus able to handle fine pitches and high-speed testing as well as have an extended
5 lifespan. The socket device for testing a circuit of an electronic device according to one aspect of the present invention may comprise: a MEMS pin having an upper body, a lower body, and an elastic connection member for connecting the upper body and the lower body; a rubber layer having a through-hole in which the MEMS pin is embedded while supported in a standing position; and a metal powder layer including a plurality
10 of metal powder particles and fixed between the MEMS pin and the rubber layer so as to surround the MEMS pin.

FIG. 3